

MacuSpec VF-TH 200

Simultaneous Through Hole Plating and Via Filling Copper Metallization

MacDermid Enthone's **MacuSpec VF-TH 200** is the metallization process to choose when efficiency, reliability and cost savings are the goal. Developed from patented technologies and in-depth technical experience, VF-TH 200 is capable of simultaneously filling vias and plating through holes with electrolytic copper that has great physical properties and a wide range of structure sizes. Beyond the increased performance, VF-TH 200 boasts savings in cycle time, processing costs and increased reliability.



	Break Force (N)	Elongation (%)	Tensile Strength (MPa)	Approx. Thickness (microns)
1	279	19.68	295	79
2	276	22.42	306	75
3	265	19.67	274	81
4	270	18.67	296	76
5	272	21.72	307	74
6	257	21.91	287	75
7	259	20.14	286	75
8	279	18.94	303	77
9	271	18.83	288	78
10	252	20.73	268	78
Mean	268	20.28	291	77

VF-TH 200 passes IPC 6012D, DS, DA and 6013D. More than 276 MPa [40,000 PSI], and greater than 18% elongation.



MacuSpec VF-TH 200 can fill 3x3 mil to 5x3 mil vias in less than 60 minutes with optimal physical properties and structural attributes.



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